Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

16-Bit Digital Signal Controllers (up to 16-Kbyte Flash and up to 2-Kbyte SRAM) with High-Speed PWM, ADC and Comparators

Operating Conditions

- 3.0V to 3.6V, -40ºC to +150ºC, DC to 20 MIPS
- 3.0V to 3.6V, -40ºC to +125ºC, DC to 40 MIPS
- 3.0V to 3.6V, -40ºC to +85ºC, DC to 50 MIPS

Core: 16-Bit dsPIC33F CPU

- Code-Efficient (C and Assembly) Architecture
- Two 40-Bit Wide Accumulators
- Single-Cycle (MAC/MPY) with Dual Data Fetch
- Single-Cycle Mixed-Sign MUL plus Hardware Divide
- 32-Bit Multiply Support

Clock Management

- ±2.0% Internal Oscillator
- Programmable PLLs and Oscillator Clock Sources
- Fail-Safe Clock Monitor (FSCM)
- Independent Watchdog Timer (WDT)
- Fast Wake-up and Start-up

Power Management

- Low-Power Management modes (Sleep, Idle, Doze)
- Integrated Power-on Reset and Brown-out Reset

High-Speed PWM

- Up to Four PWM Pairs with Independent Timing
- Dead Time for Rising and Falling Edges
- 1.04 ns PWM Resolution
- PWM Support for:
  - DC/DC, AC/DC, Inverters, PFC and Lighting
- Programmable Fault Inputs
- Flexible Trigger Configurations for ADC Conversions

Advanced Analog Features

- ADC module:
  - 10-bit resolution with up to 2 Successive Approximation Register (SAR) converters (4 Msps) and up to six Sample-and-Hold (S&H) circuits
  - Up to 12 input channels grouped into six conversion pairs, plus two voltage reference monitoring inputs
  - Dedicated result buffer for each analog channel
- Flexible and Independent ADC Trigger Sources

Advanced Analog Features (Continued)

- Up to Four High-Speed Comparators with Direct Connection to the PWM module:
  - Programmable references with 1024 voltage points

Timers/Output Compare/Input Capture

- Three General Purpose Timers:
  - Three 16-bit and one 32-bit timer/counter
- Two Output Compare (OC) modules
- Two Input Capture (IC) modules
- Peripheral Pin Select (PPS) to allow Function Remap

Communication Interfaces

- UART module (12.5 Mbps):
  - With support for LIN/J2602 protocols and IrDA®
- 4-Wire SPI module
- I^2C™ module (up to 1 Mbaud) with SMBus Support
- PPS to allow Function Remap

Input/Output

- Sink/Source 18 mA on 8 Pins, 10 mA on 10 Pins and 6 mA on 17 Pins
- 5V Tolerant Pins
- Selectable Open-Drain and Pull-ups
- External Interrupts on up to 30 I/O Pins

Qualification and Class B Support

- AEC-Q100 REVG (Grade 1, -40ºC to +125ºC)
- AEC-Q100 REVG (Grade 0, -40ºC to +150ºC)
- Class B Safety Library, IEC 60730, VDE Certified
- 6x6x0.5 mm UQFN Package Designed and Optimized to ease IPC9592A 2nd Level Temperature Cycle Qualification

Debugger Development Support

- In-Circuit and In-Application Programming
- Two Breakpoints
- IEEE 1149.2-Compatible (JTAG) Boundary Scan
- Trace and Run-Time Watch

dsPIC33FJ06GS101/X02 AND dsPIC33FJ16GSX02/X04 PRODUCT FAMILIES

The device names, pin counts, memory sizes and peripheral availability of each device are listed below. The following pages show their pinout diagrams.

TABLE 1: dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 CONTROLLER FAMILIES

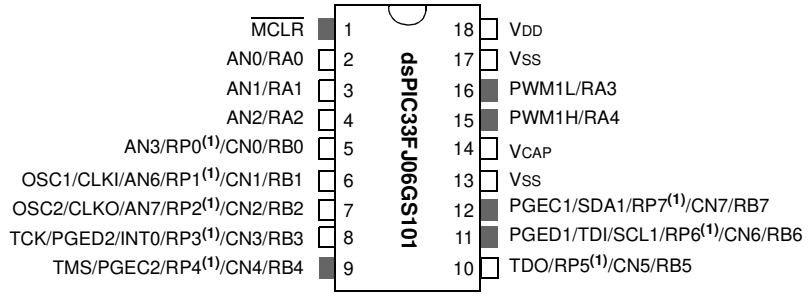
Device	Pins	Program Flash Memory (Kbytes)	RAM (Bytes)	Remappable Peripherals									DAC Output	I^2C™	ADC			I/O Pins	Packages
				Remappable Pins	16-Bit Timer	Input Capture	Output Compare	UART	SPI	PWM(2)	Analog Comparator	External Interrupts(3)			SARs	Sample-and-Hold (S&H) Circuit	Analog-to-Digital Inputs		
dsPIC33FJ06GS101	18	6	256	8	2	0	1	1	1	2x2(1)	0	3	0	1	1	3	6	13	SOIC
dsPIC33FJ06GS102	28	6	256	16	2	0	1	1	1	2x2	0	3	0	1	1	3	6	21	SPDIP, SOIC, QFN-S
dsPIC33FJ06GS202	28	6	1K	16	2	1	1	1	1	2x2	2	3	1	1	1	3	6	21	SPDIP, SOIC, QFN-S
dsPIC33FJ16GS402	28	16	2K	16	3	2	2	1	1	3x2	0	3	0	1	1	4	8	21	SPDIP, SOIC, QFN-S
dsPIC33FJ16GS404	44	16	2K	30	3	2	2	1	1	3x2	0	3	0	1	1	4	8	35	QFN, TQFP, VTLA
dsPIC33FJ16GS502	28	16	2K	16	3	2	2	1	1	4x2(1)	4	3	1	1	2	6	8	21	SPDIP, SOIC, QFN-S, UQFN
dsPIC33FJ16GS504	44	16	2K	30	3	2	2	1	1	4x2(1)	4	3	1	1	2	6	12	35	QFN, TQFP, VTLA

Note 1: The PWM4H:PWM4L pins are remappable.
2: The PWM Fault pins and PWM synchronization pins are remappable.
3: Only two out of three interrupts are remappable.

Pin Diagrams

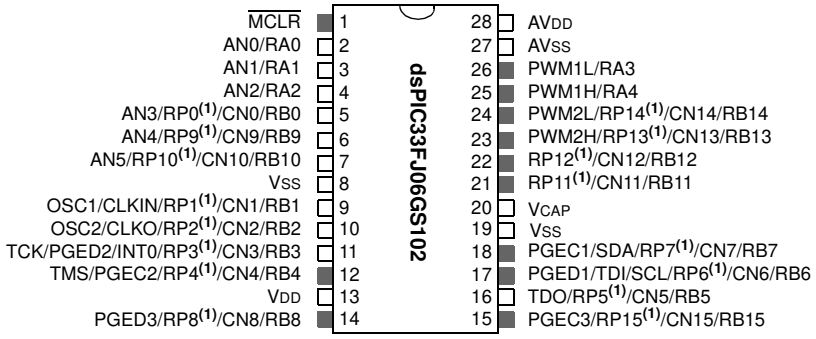
18-Pin SOIC

■ = Pins are up to 5V tolerant



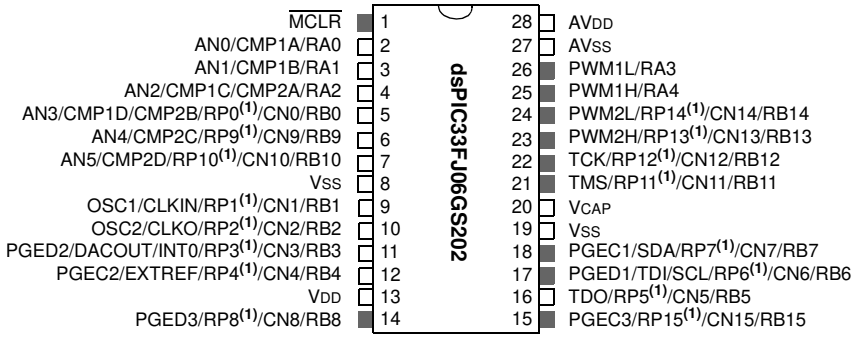
28-Pin SOIC, SPDIP

■ = Pins are up to 5V tolerant



28-Pin SPDIP, SOIC

■ = Pins are up to 5V tolerant

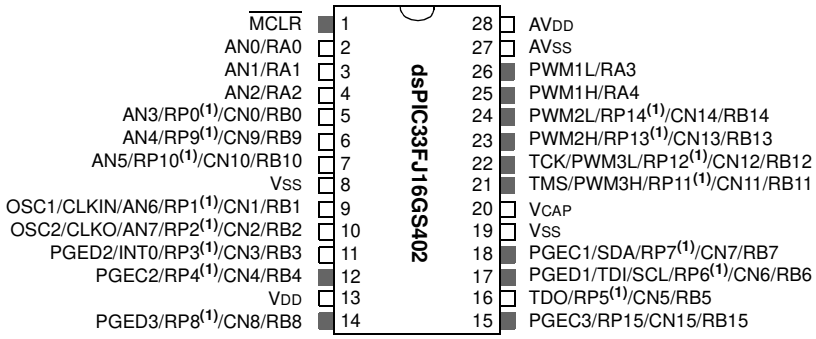


Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

Pin Diagrams (Continued)

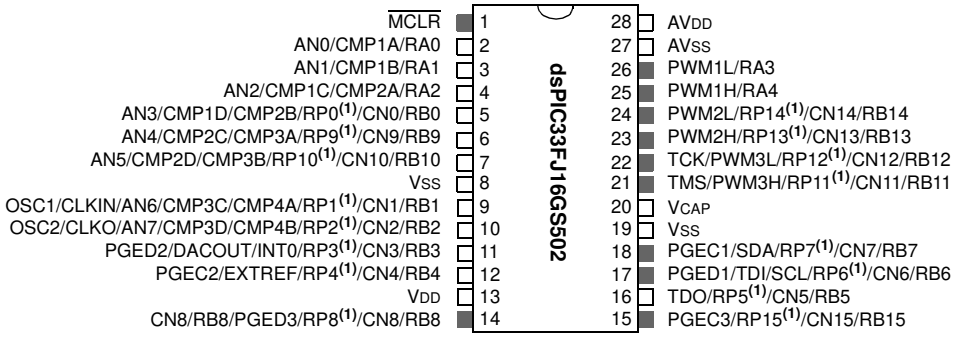
28-Pin SPDIP, SOIC

■ = Pins are up to 5V tolerant



28-Pin SPDIP, SOIC

■ = Pins are up to 5V tolerant

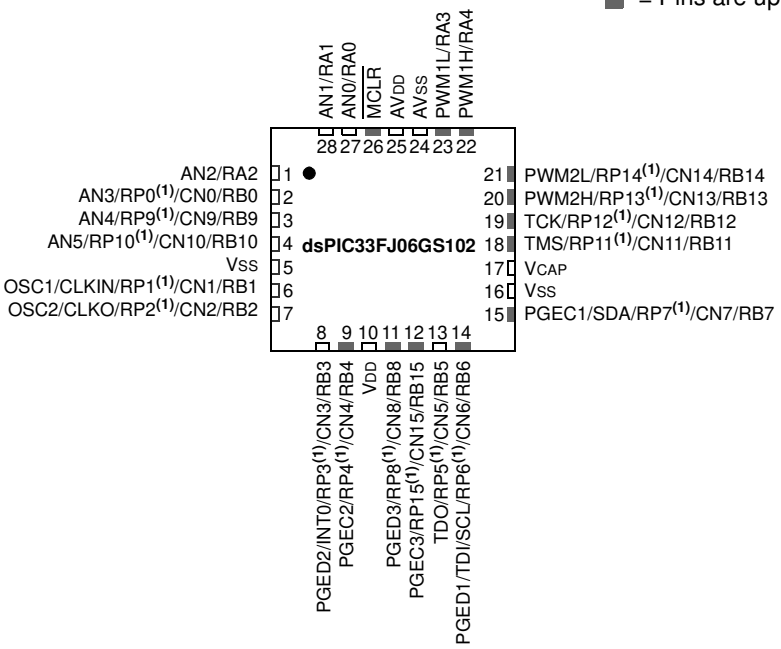


Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

Pin Diagrams (Continued)

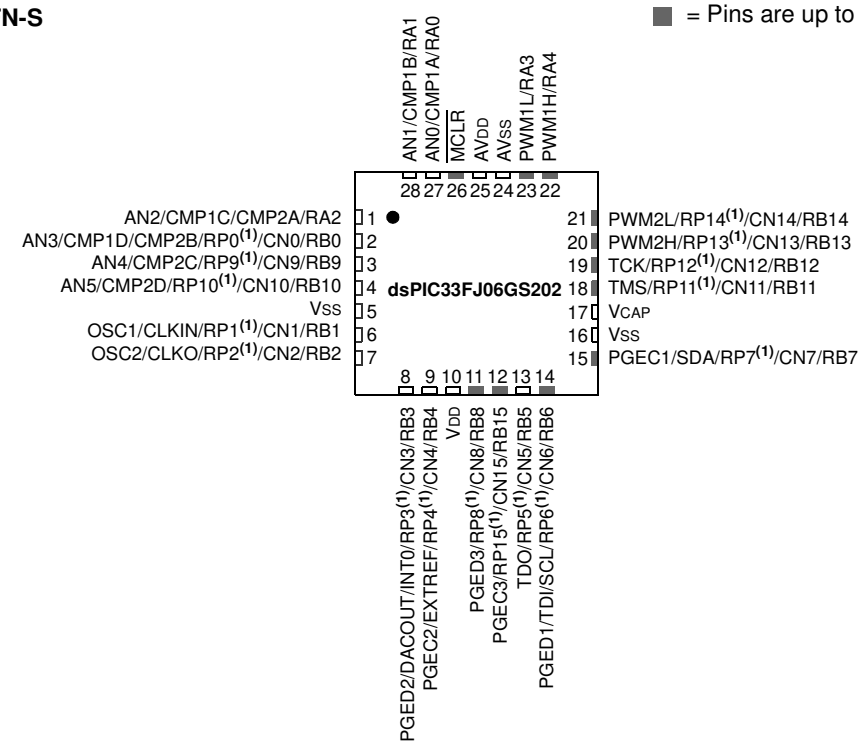
28-Pin QFN-S(2)

■ = Pins are up to 5V tolerant



28-Pin QFN-S

■ = Pins are up to 5V tolerant



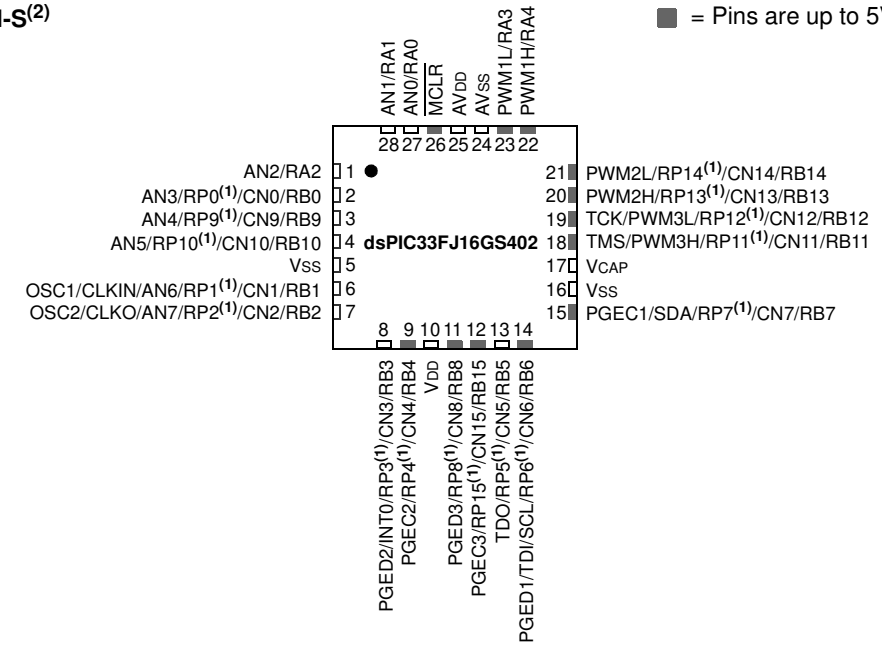
Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

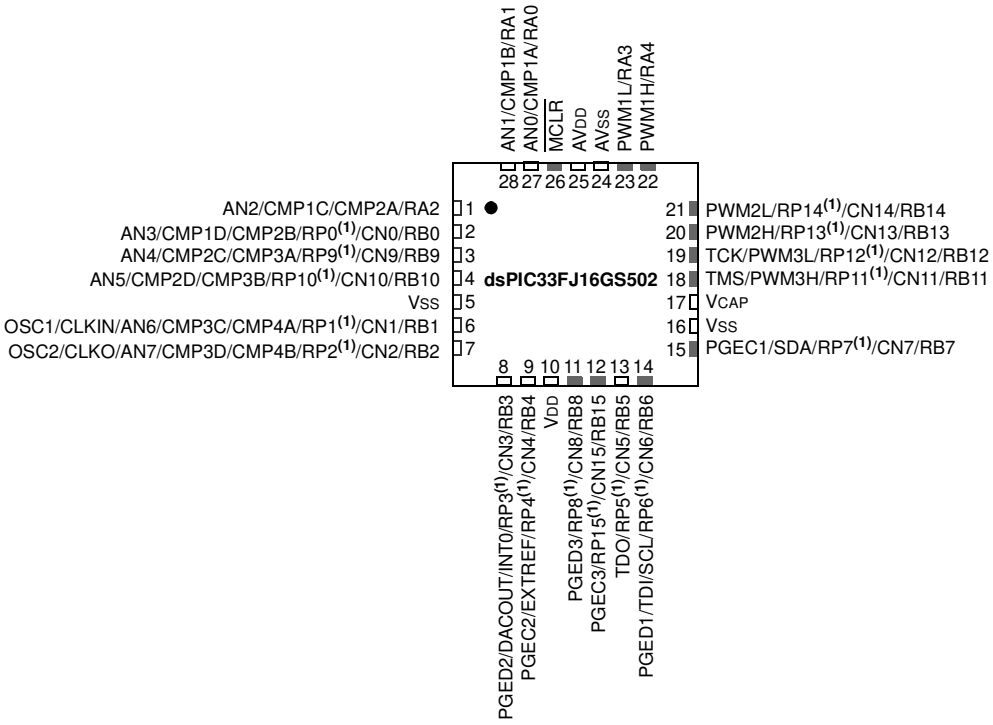
28-Pin QFN-S(2)

= Pins are up to 5V tolerant



28-Pin QFN-S, UQFN(2,3)

= Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

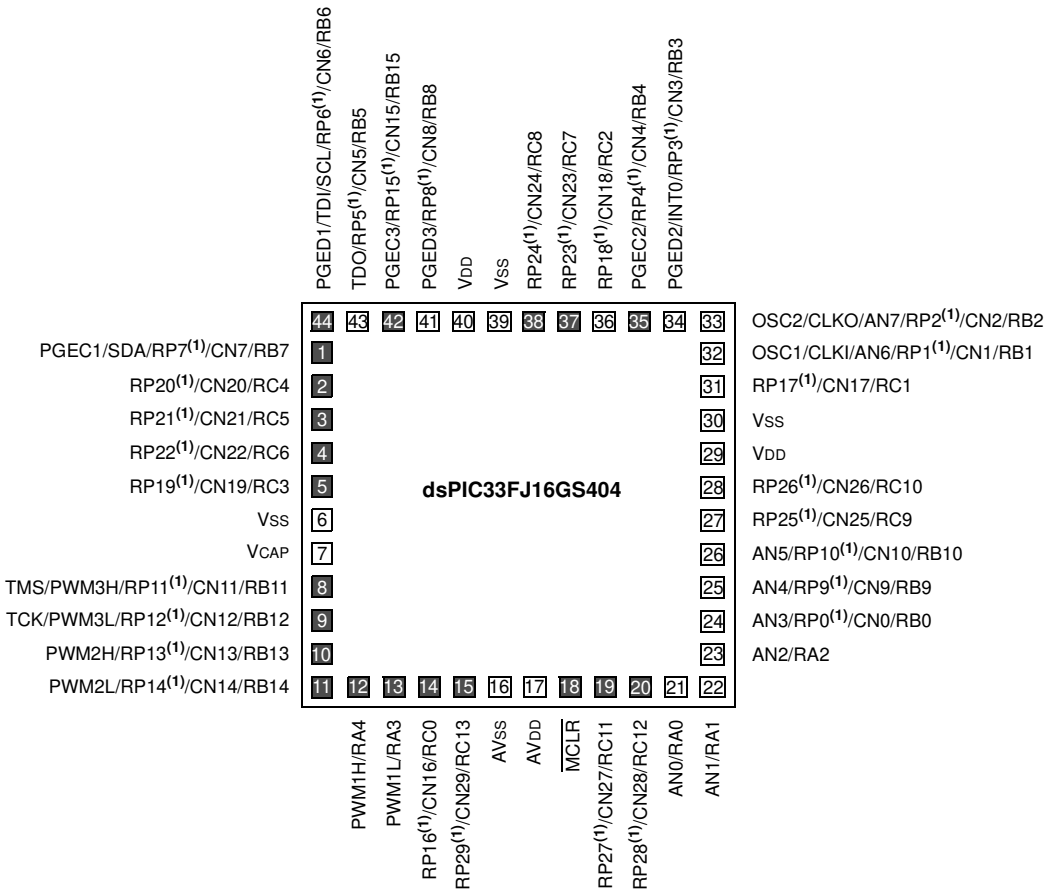
2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

3: This package is available only in Extended temperature and not Industrial temperature (applies to dsPIC33FJ16GS502 UQFN package only).

Pin Diagrams (Continued)

44-Pin VTLA(2)

■ = Pins are up to 5V tolerant



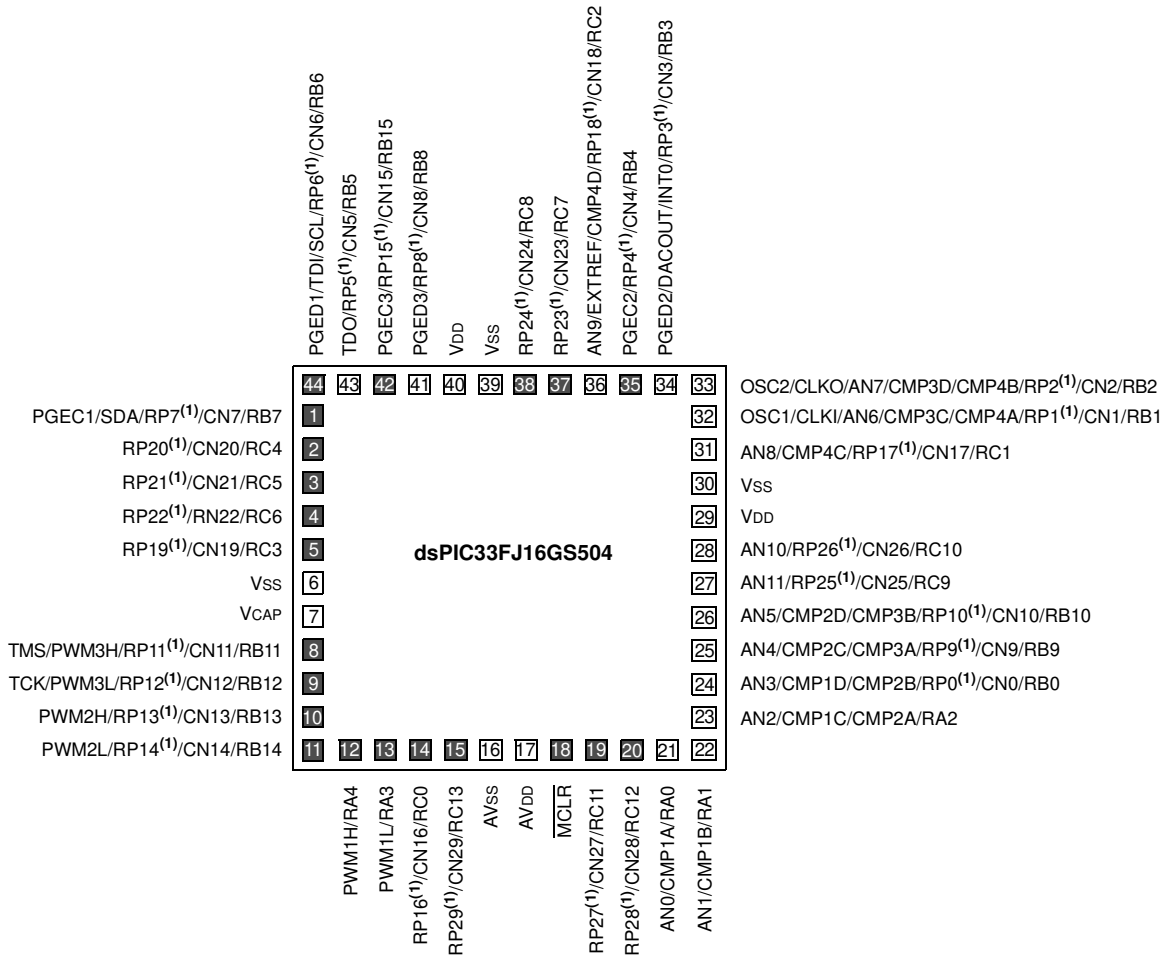
Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

44-Pin VTLA(2)

■ = Pins are up to 5V tolerant



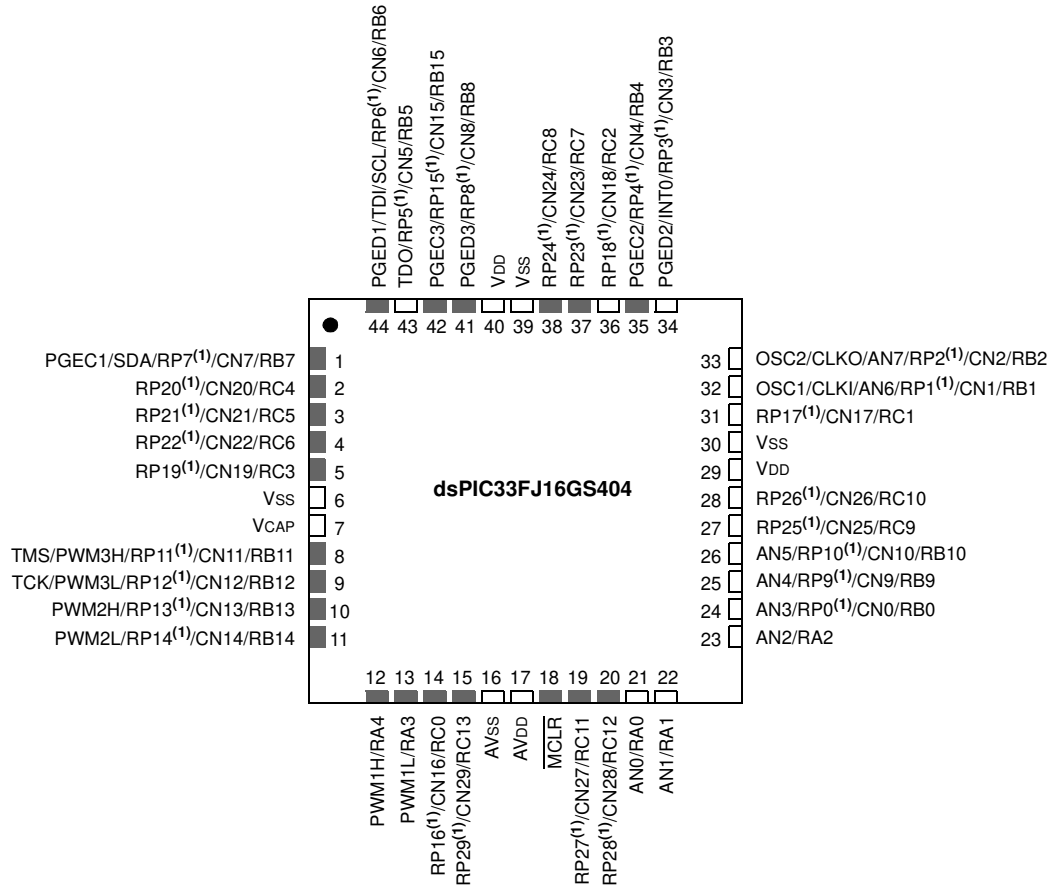
Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

44-Pin QFN(2)

■ = Pins are up to 5V tolerant



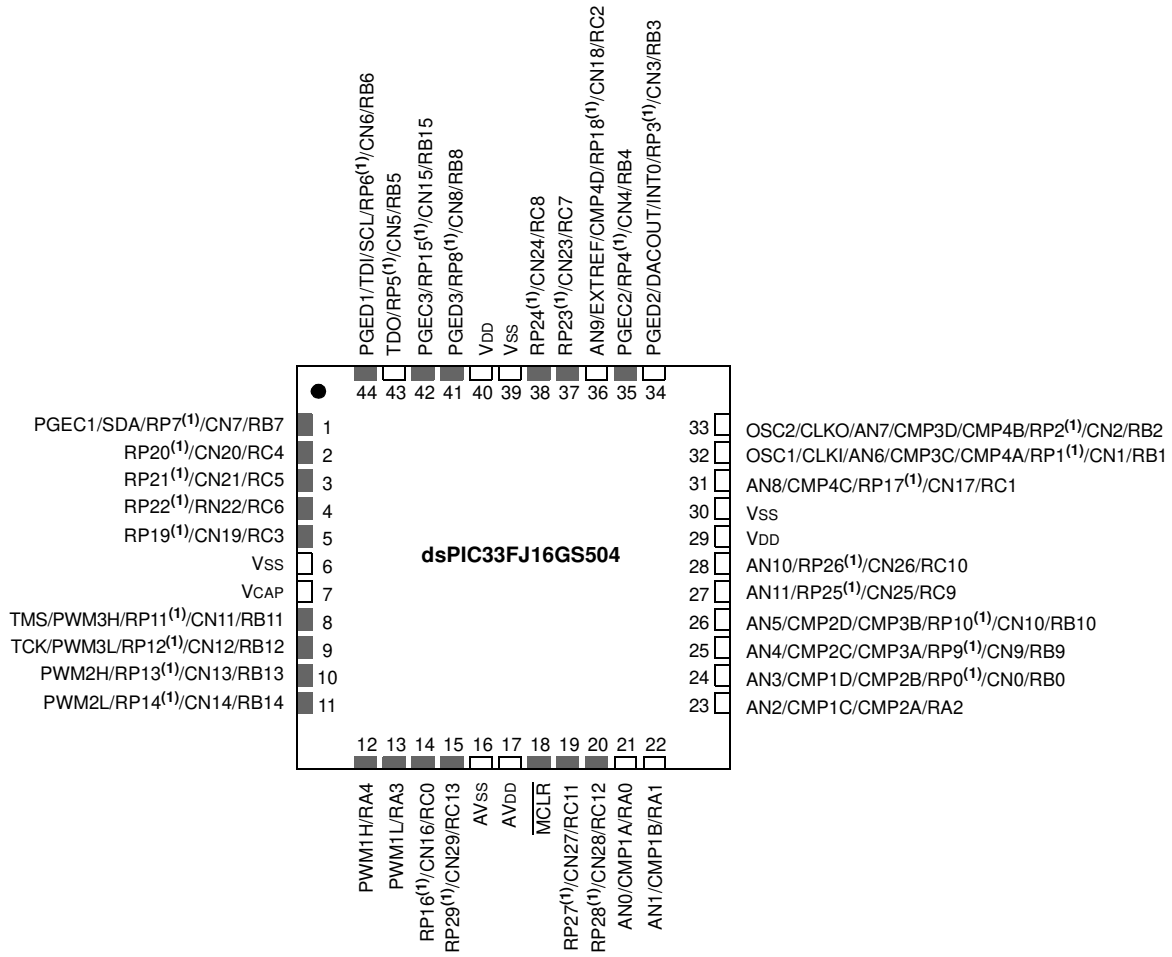
Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

44-Pin QFN(2)

■ = Pins are up to 5V tolerant



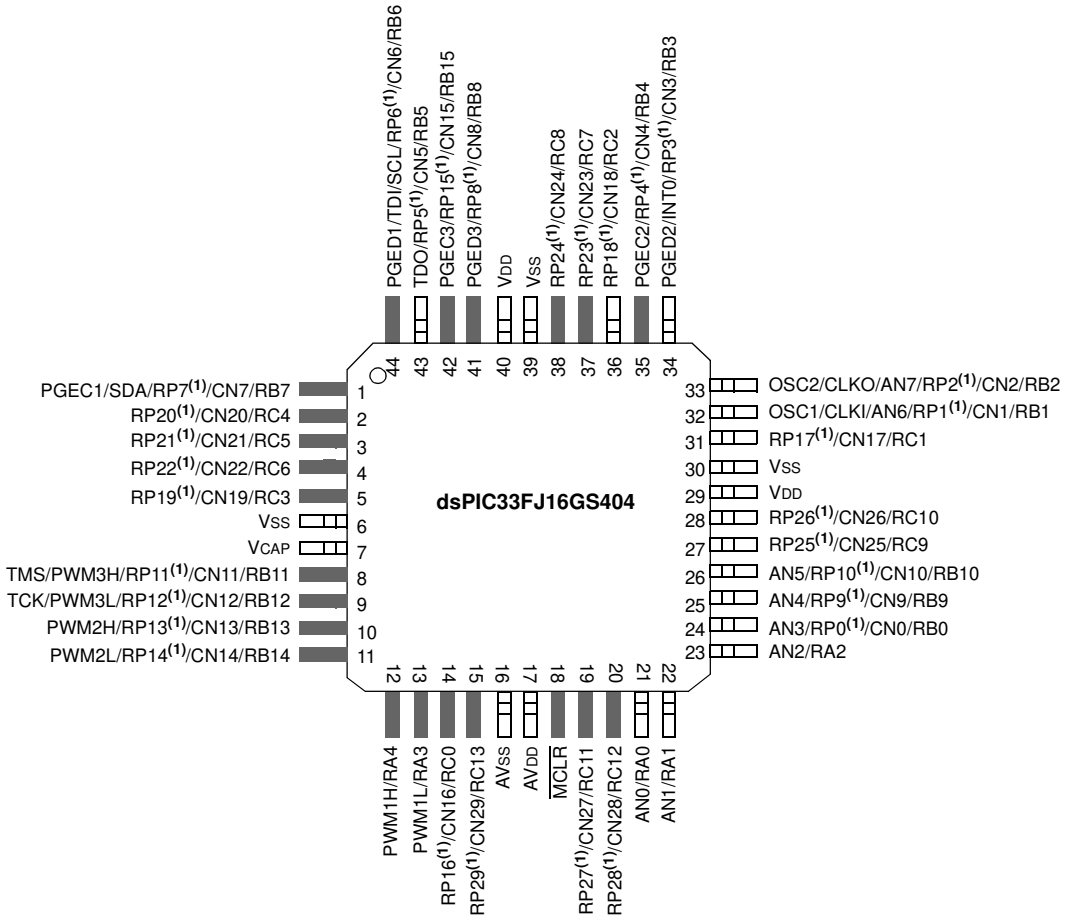
Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

44-Pin TQFP

■ = Pins are up to 5V tolerant

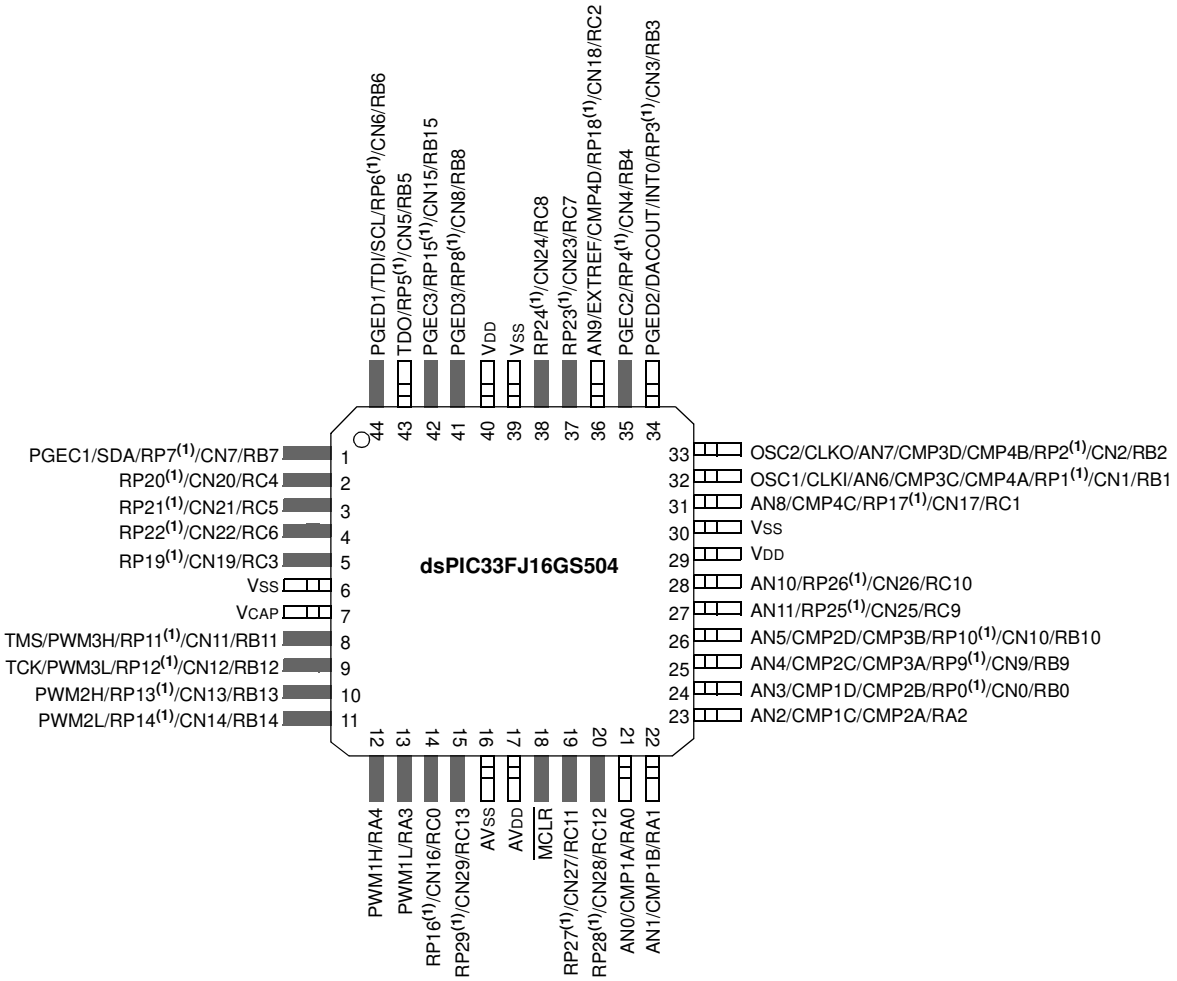


Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

Pin Diagrams (Continued)

44-Pin TQFP

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

Table of Contents

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@microchip.com**. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000000A is version A of document DS30000000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; **http://www.microchip.com**
- Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at **www.microchip.com** to receive the most current information on all of our products.

Referenced Sources

This device data sheet is based on the following individual chapters of the *"dsPIC33/PIC24 Family Reference Manual"*. These documents should be considered as the primary reference for the operation of a particular module or device feature.

Note: To access the documents listed below, browse to the documentation section of the dsPIC33FJ16GS504 product page of the Microchip web site (www.microchip.com).

In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- **"Introduction"** (DS70197)
- **"CPU"** (DS70204)
- **"Data Memory"** (DS70202)
- **"Program Memory"** (DS70203)
- **"Flash Programming"** (DS70191)
- **"Reset"** (DS70192)
- **"Watchdog Timer (WDT) and Power-Saving Modes"** (DS70196)
- **"I/O Ports"** (DS70193)
- **"Timers"** (DS70205)
- **"Input Capture"** (DS70198)
- **"Output Compare"** (DS70005157)
- **"Analog-to-Digital Converter (ADC)"** (DS70621)
- **"UART"** (DS70188)
- **"Serial Peripheral Interface (SPI)"** (DS70206)
- **"Inter-Integrated Circuit™ (I^2C™)"** (DS70000195)
- **"CodeGuard™ Security** (DS70199)
- **"Programming and Diagnostics"** (DS70207)
- **"Device Configuration"** (DS70194)
- **"Interrupts (Part IV)"** (DS70300)
- **"Oscillator (Part IV)"** (DS70307)
- **"High- Speed PWM Module"** (DS70000323)
- **"High-Speed 10-Bit ADC"** (DS70000321)
- **"High-Speed Analog Comparator"** (DS70296)
- **"Oscillator (Part VI)"** (DS70644)

NOTES:

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest *"dsPIC33F/PIC24H Family Reference Manual"* sections.

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

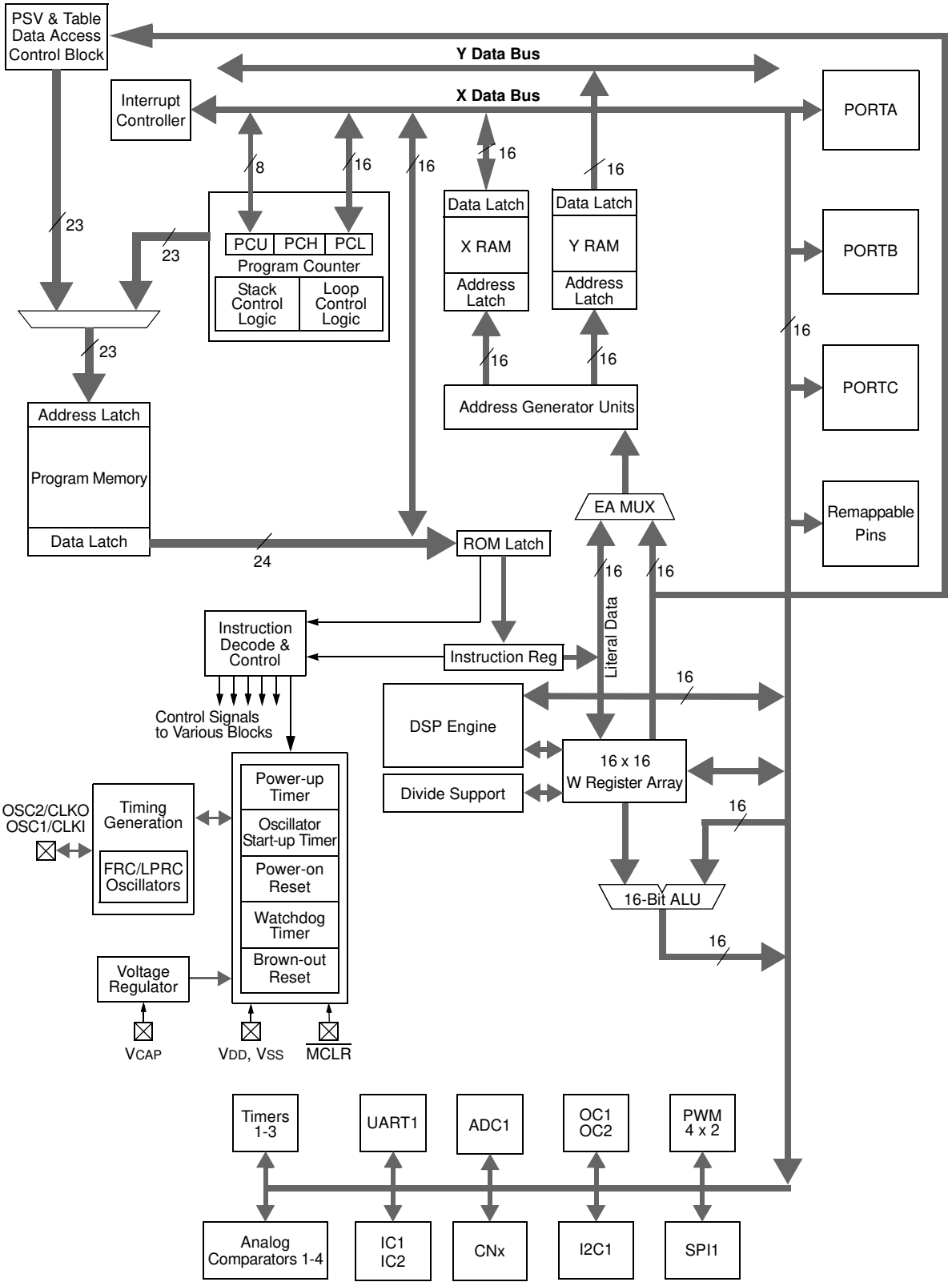
This document contains device-specific information for the following dsPIC33F Digital Signal Controller (DSC) devices:

- dsPIC33FJ06GS101
- dsPIC33FJ06GS102
- dsPIC33FJ06GS202
- dsPIC33FJ16GS402
- dsPIC33FJ16GS404
- dsPIC33FJ16GS502
- dsPIC33FJ16GS504

dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit microcontroller (MCU) architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules in the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 devices. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 BLOCK DIAGRAM



Note: Not all pins or features are implemented on all device pinout configurations. See pinout diagrams for the specific pins and features present on each device.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Type	Buffer Type	PPS Capable	Description
AN0-AN11	I	Analog	No	Analog input channels
CLKI	I	ST/CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
CN0-CN29	I	ST	No	Change Notification inputs. Can be software programmed for internal weak pull-ups on all inputs.
IC1-IC2	I	ST	Yes	Capture Inputs 1/2.
OCFA	I	ST	Yes	Compare Fault A input (for Compare Channels 1 and 2)
OC1-OC2	O	—	Yes	Compare Outputs 1 through 2.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
RA0-RA4	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC13	I/O	ST	No	PORTC is a bidirectional I/O port.
RP0-RP29	I/O	ST	No	Remappable I/O pins.
T1CK	I	ST	Yes	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	Yes	Timer3 external clock input.
$\overline{\text{U1CTS}}$	I	ST	Yes	UART1 Clear-To-Send.
$\overline{\text{U1RTS}}$	O	—	Yes	UART1 Ready-To-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
SCK1	I/O	ST	Yes	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	Yes	SPI1 data in.
$\overline{\text{SDO1}}$	O	—	Yes	SPI1 data out.
$\overline{\text{SS1}}$	I/O	ST	Yes	SPI1 slave synchronization or frame pulse I/O.
SCL1	I/O	ST	No	Synchronous serial clock input/output for I2C1.
SDA1	I/O	ST	No	Synchronous serial data input/output for I2C1.
TMS	I	TTL	No	JTAG Test mode select pin.
TCK	I	TTL	No	JTAG test clock input pin.
TDI	I	TTL	No	JTAG test data input pin.
TDO	O	—	No	JTAG test data output pin.

Legend: CMOS = CMOS compatible input or output
Analog = Analog input
I = Input
ST = Schmitt Trigger input with CMOS levels
P = Power
O = Output
TTL = Transistor-Transistor Logic
PPS = Peripheral Pin Select

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	PPS Capable	Description
CMP1A	I	Analog	No	Comparator 1 Channel A.
CMP1B	I	Analog	No	Comparator 1 Channel B.
CMP1C	I	Analog	No	Comparator 1 Channel C.
CMP1D	I	Analog	No	Comparator 1 Channel D.
CMP2A	I	Analog	No	Comparator 2 Channel A.
CMP2B	I	Analog	No	Comparator 2 Channel B.
CMP2C	I	Analog	No	Comparator 2 Channel C.
CMP2D	I	Analog	No	Comparator 2 Channel D.
CMP3A	I	Analog	No	Comparator 3 Channel A.
CMP3B	I	Analog	No	Comparator 3 Channel B.
CMP3C	I	Analog	No	Comparator 3 Channel C.
CMP3D	I	Analog	No	Comparator 3 Channel D.
CMP4A	I	Analog	No	Comparator 4 Channel A.
CMP4B	I	Analog	No	Comparator 4 Channel B.
CMP4C	I	Analog	No	Comparator 4 Channel C.
CMP4D	I	Analog	No	Comparator 4 Channel D.
DACOUT	O	—	No	DAC output voltage.
ACMP1-ACMP4	O	—	Yes	DAC trigger to PWM module.
EXTREF	I	Analog	No	External voltage reference input for the reference DACs.
REFCLKO	O	—	Yes	REFCLKO output signal is a postscaled derivative of the system clock.
FLT1-FLT8	I	ST	Yes	Fault Inputs to PWM module.
SYNCI1-SYNCI2	I	ST	Yes	External synchronization signal to PWM master time base.
SYNCO1	O	—	Yes	PWM master time base for external device synchronization.
PWM1L	O	—	No	PWM1 low output.
PWM1H	O	—	No	PWM1 high output.
PWM2L	O	—	No	PWM2 low output.
PWM2H	O	—	No	PWM2 high output.
PWM3L	O	—	No	PWM3 low output.
PWM3H	O	—	No	PWM3 high output.
PWM4L	O	—	Yes	PWM4 low output.
PWM4H	O	—	Yes	PWM4 high output.
PGED1	I/O	ST	No	Data I/O pin for programming/debugging Communication Channel 1.
PGEC1	I	ST	No	Clock input pin for programming/debugging Communication Channel 1.
PGED2	I/O	ST	No	Data I/O pin for programming/debugging Communication Channel 2.
PGEC2	I	ST	No	Clock input pin for programming/debugging Communication Channel 2.
PGED3	I/O	ST	No	Data I/O pin for programming/debugging Communication Channel 3.
PGEC3	I	ST	No	Clock input pin for programming/debugging Communication Channel 3.
$\overline{MCLR}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AV_{DD}	P	P	No	Positive supply for analog modules. This pin must be connected at all times. AV_{DD} is connected to V_{DD}.
AV_{SS}	P	P	No	Ground reference for analog modules. AV_{SS} is connected to V_{SS}.
V_{DD}	P	—	No	Positive supply for peripheral logic and I/O pins.
V_{CAP}	P	—	No	CPU logic filter capacitor connection.
V_{SS}	P	—	No	Ground reference for logic and I/O pins.

Legend: CMOS = CMOS compatible input or output
Analog = Analog input
I = Input
ST = Schmitt Trigger input with CMOS levels
P = Power
O = Output
TTL = Transistor-Transistor Logic
PPS = Peripheral Pin Select

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 family of 16-bit Digital Signal Controllers (DSC) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP™ Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

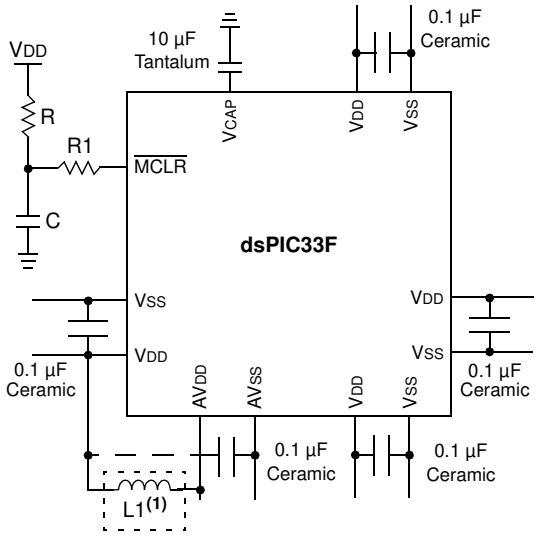
2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2} \quad \text{(i.e., ADC conversion rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f \sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

A low-ESR (<5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 24.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 21.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

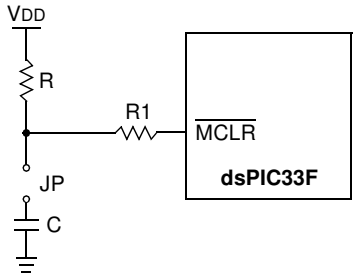
- Device Reset
- Device programming and debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor, C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

2.5 ICSP™ Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB® REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

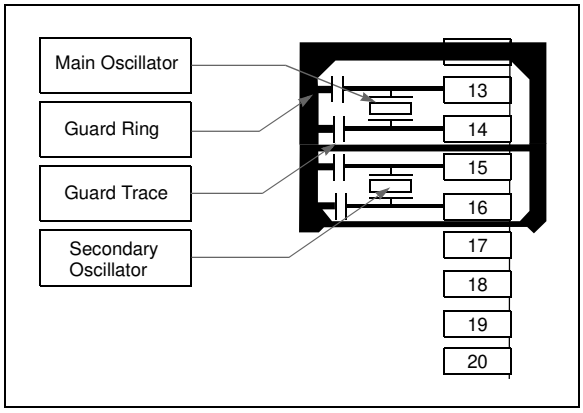
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 4 MHz < FIN < 8 MHz to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV, and PLLFBD to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

2.8 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 2, ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the A/D input pins (ANx) as “digital” pins, by setting all bits in the ADPCFG register.

The bits in the registers that correspond to the A/D pins that are initialized by MPLAB ICD 2, ICD 3, or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain A/D pins as analog input pins during the debug session, the user application must clear the corresponding bits in the ADPCFG register during initialization of the ADC module.

When MPLAB ICD 2, ICD 3, or REAL ICE is used as a programmer, the user application firmware must correctly configure the ADPCFG register. Automatic initialization of these registers is only done during debugger operation. Failure to correctly configure the register(s) will result in all A/D pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.9 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic-low state.

Alternatively, connect a 1k to 10k resistor between VSS and unused pins and drive the output to logic low.

2.10 Typical Application Connection Examples

Examples of typical application connections are shown in Figure 2-4 through Figure 2-11.

FIGURE 2-4: DIGITAL PFC

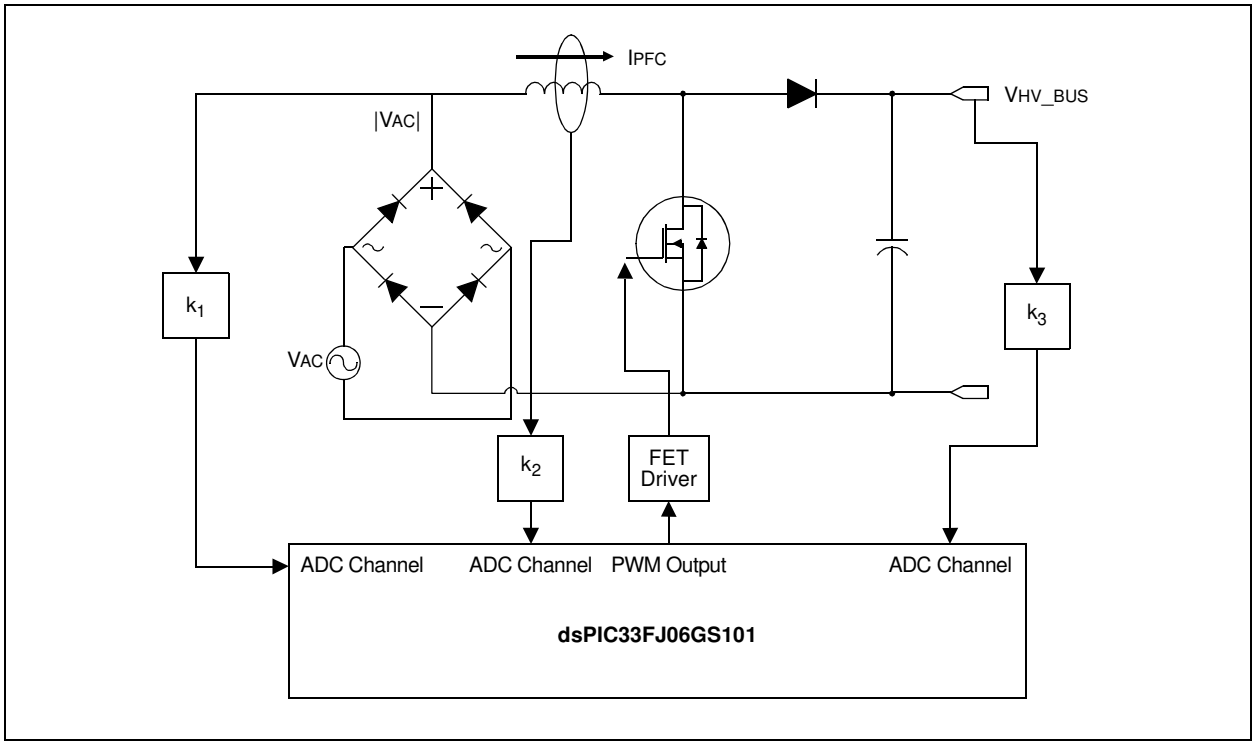


FIGURE 2-5: BOOST CONVERTER IMPLEMENTATION